

MOSFET - N-Channel, POWERTRENCH®, Logic Level

FDN359BN

General Description

This N-Channel Logic Level MOSFET is produced using **onsemi**'s advanced POWERTRENCH process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Features

- 2.7 A, 30 V
 - $R_{DS(ON)} = 0.046 \Omega @ V_{GS} = 10 V$
 - $R_{DS(ON)} = 0.060 \Omega @ V_{GS} = 4.5 V$
- Very Fast Switching Speed
- Low Gate Charge (5 nC Typical)
- High Performance Version of Industry Standard SOT-23 Package.
 Identical Pin Out to SOT-23 with 30% Higher Power Handling Capability
- This Device is Pb-Free and Halide Free

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$, unless otherwise noted)

Symbol	Para	Value	Unit	
V_{DSS}	Drain-Source Voltage	30	٧	
V _{GSS}	Gate-Source Voltage	±20	٧	
I _D	Maximum Drain Current	Continuous (Note 1a)	2.7	Α
	Current	Pulsed	15	
P _D	Maximum Power	(Note 1a)	0.5	W
	Dissipation	(Note 1b)	0.46	
T_J , T_{STG}	Operating and Storag	-55 to +150	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted)

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	250	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	75	°C/W

V _{DSS}	R _{DS(ON)} MAX	I _D MAX
30 V	0.046 Ω @ 10 V	2.7 A
	0.060 Ω @ 4.5 V	



SOT-23/SUPERSOT™-23, 3 LEAD, 1.4x2.9 CASE 527AG

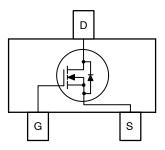
MARKING DIAGRAM



359B = Specific Device Code M = Month Code ■ Pb-Free Package

(Note: Microdot may be in either location)

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARA	ACTERISTICS				•	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	30	-	_	V
ΔBV_{DSS}	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	21	_	mV/°C
ΔT_{J}						
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V	_	-	1	μΑ
		$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_J = -55^{\circ}\text{C}$	-	-	10	
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	-	±100	nA
ON CHARAC	CTERISTICS (Note 2)	_	_	_	_	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1	1.8	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_{J}}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	-	-4	-	mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.7 A	_	0.026	0.046	Ω
, ,		V _{GS} = 4.5 V, I _D = 2.4 A,	_	0.032	0.060	
		V _{GS} = 10 V, I _D = 2.7 A, T _J = 125°C	-	0.033	0.075	
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 5 V	15	-	-	Α
9FS	Forward Transconductance	V _{DS} = 5 V, I _D = 2.7 A	-	11	_	S
DYNAMIC CI	HARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 15 V, V _{GS} = 0 V, f = 1.0 MHz	_	485	650	pF
Coss	Output Capacitance		-	105	140	pF
C _{rss}	Reverse Transfer Capacitance		-	65	100	pF
R_{G}	Gate Resistance	f = 1.0 MHz		1.8		Ω
SWITCHING	CHARACTERISTICS (Note 2)					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 15 V, I _D = 1 A,	_	7	14	ns
t _r	Turn-On Rise Time	V_{GS} = 10 V, R_{GEN} = 6 Ω	-	5	10	ns
t _{d(off)}	Turn-Off Delay Time		-	20	35	ns
t _f	Turn-Off Fall Time		-	2	4	ns
Q_g	Total Gate Charge	$V_{DS} = 15 \text{ V}, I_D = 2.7 \text{ A}, V_{GS} = 5 \text{ V}$	_	5	7	nC
Q_{gs}	Gate-Source Charge		-	1.3	_	nC
Q_{gd}	Gate-Drain Charge		_	1.8	_	nC
DRAIN-SOU	RCE DIODE CHARACTERISTICS AND MAXIMUI	M RATINGS				
I _S	Maximum Continuous Drain-Source Diode Forwa	ard Current	-	-	0.42	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.42 A (Note 2)	_	0.7	1.2	V
trr	Diode Reverse Recovery Time	IF = 2.7 A, diF/dt = 100 A/μs		12	20	ns
Qrr	Diode Reverse Recovery Charge			3	5	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



 a) 250°C/W when mounted on a 0.02 in² pad of 2 oz copper



b) 270°C/W when mounted on a minimum pad

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

TYPICAL CHARACTERISTICS

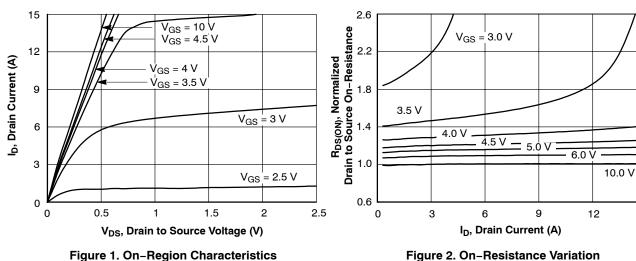
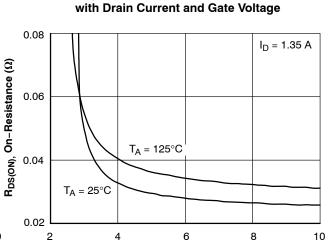


Figure 1. On-Region Characteristics

1.2



15

 $I_D = 2.7 A$ Drain to Source On-Resistance V_{GS} = 10 V R_{DS(ON)}, Normalized 0.8 0 -50 -25 25 50 75 100 125 150 T_J, Junction Temperature (°C)

Figure 3. On-Resistance Variation with Temperature

Figure 4. On-Resistance Variation with Gate-to-Source Voltage

V_{GS}, Gate to Source Voltage (V)

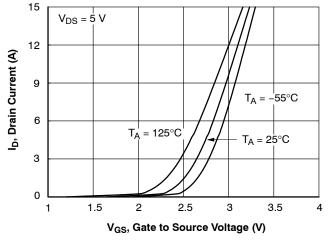


Figure 5. Transfer Characteristics

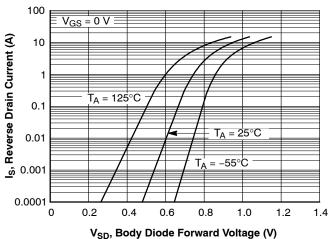
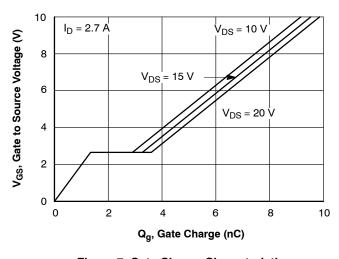


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

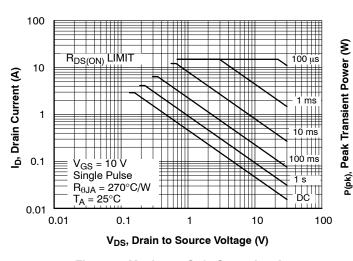
TYPICAL CHARACTERISTICS (continued)



800 f = 1 MHz V_{GS} = 0 V 600 Capacitance (pF) C_{ISS} 400 200 C_{OSS} CRSS 0 0 5 15 10 20 25 30 V_{DS}, Drain to Source Voltage (V)

Figure 7. Gate Charge Characteristics

Figure 8. Capacitance Characteristics



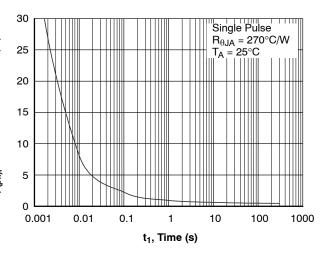


Figure 9. Maximum Safe Operating Area

Figure 10. Single Pulse Maximum Power Dissipation

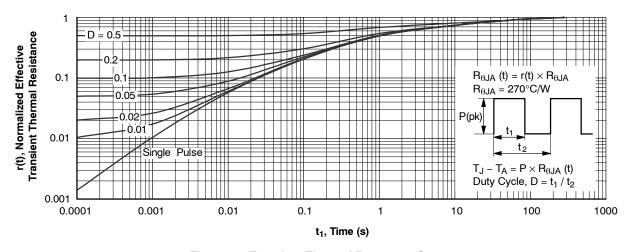


Figure 11. Transient Thermal Response Curve

NOTE: Thermal characterization performed using the conditions described in Note 1b.

Transient thermal response will change depending on the circuit board design.

PACKAGE MARKING AND ORDERING INFORMATION

I	Device	Device Marking	Package	Reel Size	Tape Width	Shipping [†]
	FDN359BN	359B	SOT-23/SUPERSOT-23, 3 LEAD, 1.4x2.9 (Pb-Free, Halide Free)	7″	8 mm	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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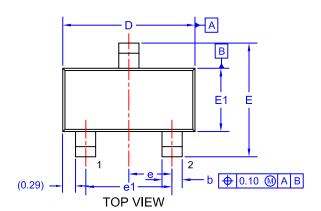






SOT-23/SUPERSOT™-23, 3 LEAD, 1.4x2.9 CASE 527AG **ISSUE A**

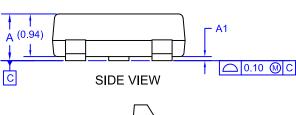
DATE 09 DEC 2019

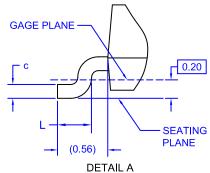


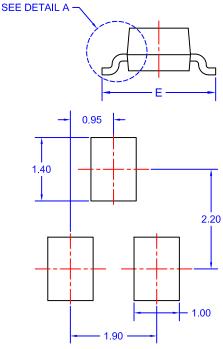
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS,
 MOLD FLASH AND TIE BAR EXTRUSIONS.

DIM	MIN.	NOM.	MAX.	
Α	0.85	0.95	1.12	
A1	0.00	0.05	0.10	
b	0.370	0.435	0.508	
С	0.085	0.150	0.180	
D	2.80	2.92	3.04	
Е	2.31	2.51	2.71	
E1	1.20	1.40	1.52	
е	0.95 BSC			
e1	1.90 BSC			
L	0.33 0.38 0.43			







LAND PATTERN RECOMMENDATION*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXM=

XXX = Specific Device Code = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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